

### General Description

The AO6408 uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge. It offers operation over a wide gate drive range from 1.8V to 12V. It is ESD protected. This device is suitable for use as a load switch.

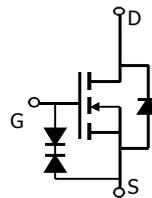
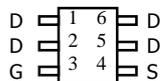
### Features

$V_{DS}$  (V) = 20V  
 $I_D = 8.8A$  ( $V_{GS} = 10V$ )  
 $R_{DS(ON)} < 18m\Omega$  ( $V_{GS} = 10V$ )  
 $R_{DS(ON)} < 20m\Omega$  ( $V_{GS} = 4.5V$ )  
 $R_{DS(ON)} < 25m\Omega$  ( $V_{GS} = 2.5V$ )  
 $R_{DS(ON)} < 32m\Omega$  ( $V_{GS} = 1.8V$ )  
 ESD Rating: 2000V HBM

ESD Protected  
 100% UIS Tested  
 100% Rg Tested



**TSOP-6  
Top View**



### Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Continuous Drain Current <sup>A</sup>	$I_D$	$T_A=25^\circ\text{C}$	8.8
		$T_A=70^\circ\text{C}$	7
Pulsed Drain Current <sup>B</sup>	$I_{DM}$	40	A
Power Dissipation	$P_D$	$T_A=25^\circ\text{C}$	2
		$T_A=70^\circ\text{C}$	1.28
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	$^\circ\text{C}$

### Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient <sup>A</sup>	$R_{\theta JA}$	$t \leq 10s$	47.5	$^\circ\text{C/W}$
Maximum Junction-to-Ambient <sup>A</sup>		Steady-State	74	$^\circ\text{C/W}$
Maximum Junction-to-Lead <sup>C</sup>	$R_{\theta JL}$	37	40	$^\circ\text{C/W}$

**Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V	20			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =16V, V <sub>GS</sub> =0V T <sub>J</sub> =55°C			10 25	μA
I <sub>GSS</sub>	Gate-Source leakage current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±10V			±10	μA
BV <sub>GSO</sub>	Gate-Source Breakdown Voltage	V <sub>DS</sub> =0V, I <sub>G</sub> =±250μA	±12			V
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> I <sub>D</sub> =250μA	0.5	0.75	1	V
I <sub>D(ON)</sub>	On state drain current	V <sub>GS</sub> =4.5V, V <sub>DS</sub> =5V	40			A
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =8.8A T <sub>J</sub> =125°C		14.4 18.5	18 23	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =8A		16	20	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =6A		20.5	25	mΩ
		V <sub>GS</sub> =1.8V, I <sub>D</sub> =4A		25.6	32	mΩ
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =8.8A		33		S
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =1A		0.72	1	V
I <sub>S</sub>	Maximum Body-Diode Continuous Current				3	A
<b>DYNAMIC PARAMETERS</b>						
C <sub>iss</sub>	Input Capacitance			1810	2200	pF
C <sub>oss</sub>	Output Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =10V, f=1MHz		232		pF
C <sub>riss</sub>	Reverse Transfer Capacitance			200		pF
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz		1.6	2.2	Ω
<b>SWITCHING PARAMETERS</b>						
Q <sub>g</sub>	Total Gate Charge			17.9	22	nC
Q <sub>gs</sub>	Gate Source Charge	V <sub>GS</sub> =4.5V, V <sub>DS</sub> =10V, I <sub>D</sub> =8.8A		1.5		nC
Q <sub>gd</sub>	Gate Drain Charge			4.7		nC
t <sub>D(on)</sub>	Turn-On DelayTime			3.3		ns
t <sub>r</sub>	Turn-On Rise Time	V <sub>GS</sub> =10V, V <sub>DS</sub> =10V, R <sub>L</sub> =1.1Ω, R <sub>GEN</sub> =3Ω		5.9		ns
t <sub>D(off)</sub>	Turn-Off DelayTime			44		ns
t <sub>f</sub>	Turn-Off Fall Time			7.7		ns
t <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> =8.8A, di/dt=100A/μs		22	27	ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge	I <sub>F</sub> =8.8A, di/dt=100A/μs		9.8		nC

A: The value of R<sub>θJA</sub> is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25° C. The value in any a given application depends on the user's specific board design. The current rating is based on the t ≤ 10s thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C: The R<sub>θJA</sub> is the sum of the thermal impedance from junction to lead R<sub>θJL</sub> and lead to ambient.

D: The static characteristics in Figures 1 to 6 are obtained using 80 μs pulses, duty cycle 0.5% max.

E: These tests are performed with the device mounted on 1 in <sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25° C. The SOA curve provides a single pulse rating. Rev3: August 2005

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

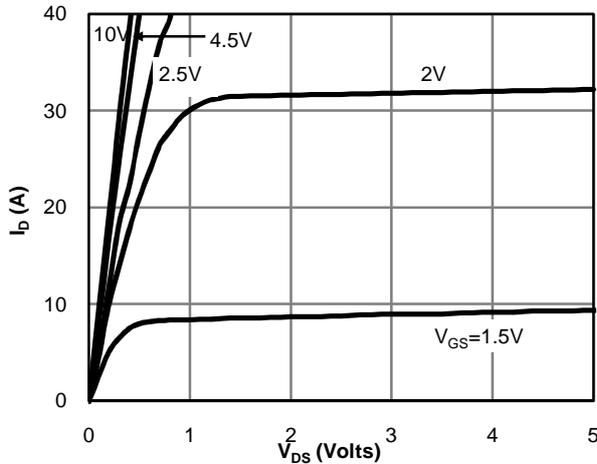


Fig 1: On-Region Characteristics

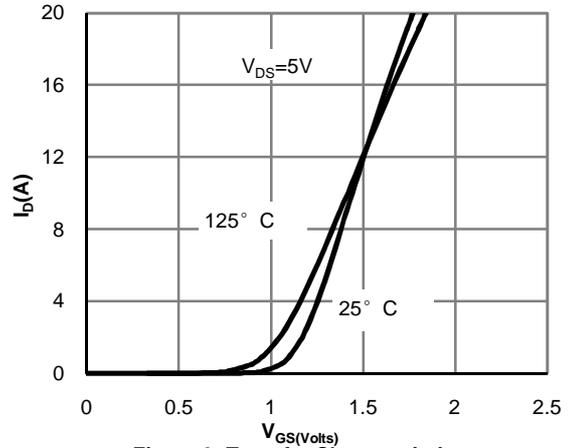


Figure 2: Transfer Characteristics

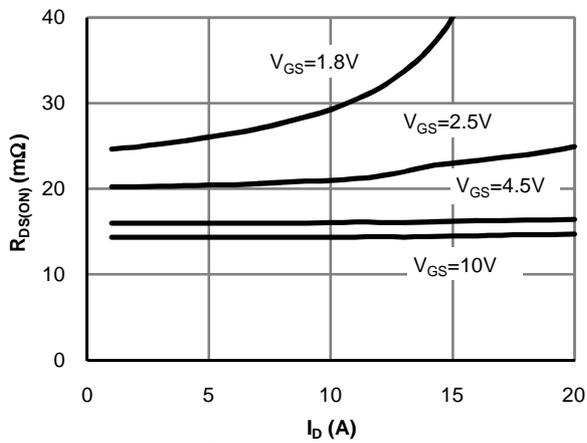


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

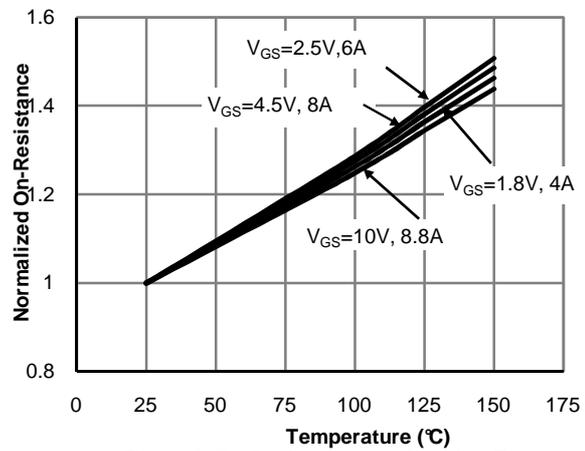


Figure 4: On-Resistance vs. Junction Temperature

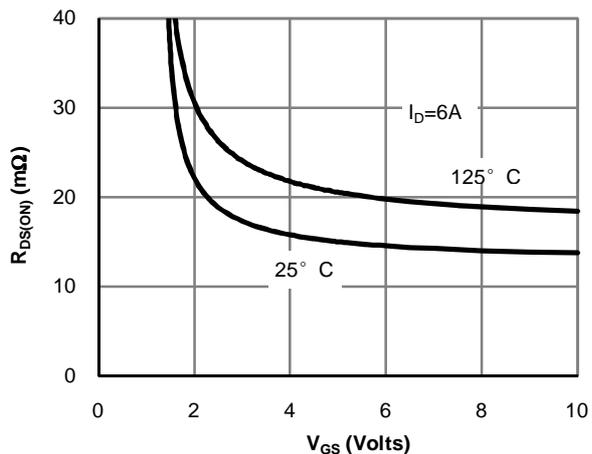


Figure 5: On-Resistance vs. Gate-Source Voltage

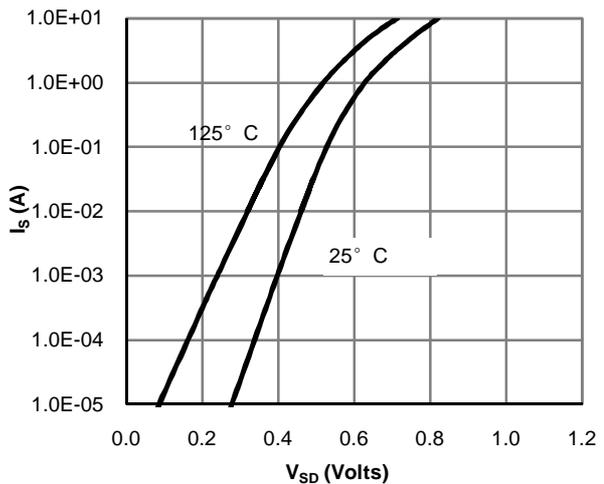
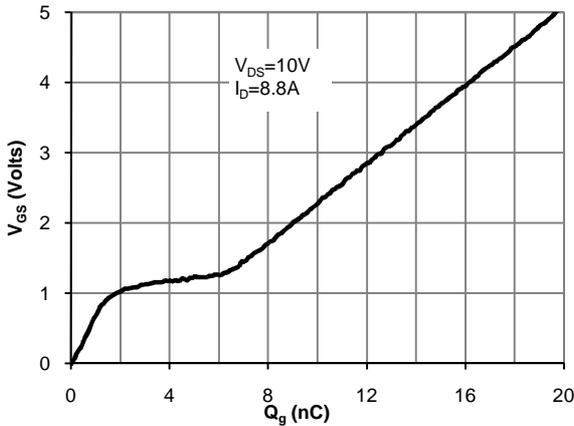
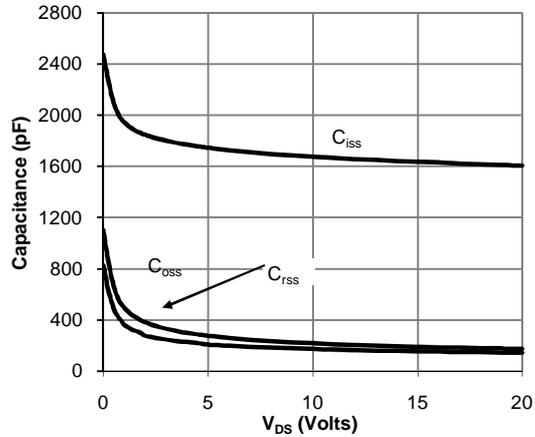


Figure 6: Body-Diode Characteristics

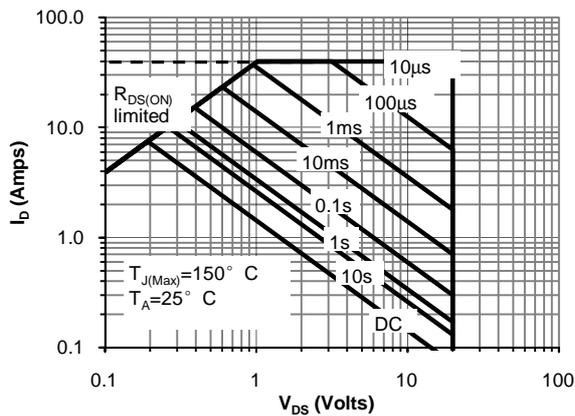
**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**



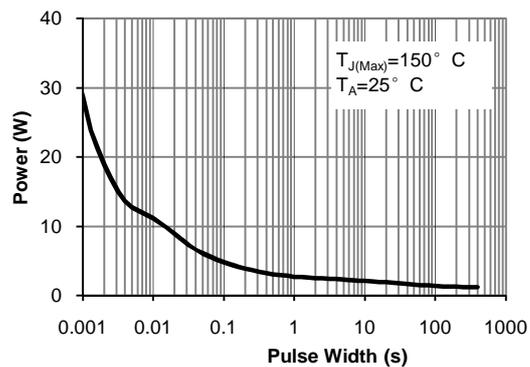
**Figure 7: Gate-Charge Characteristics**



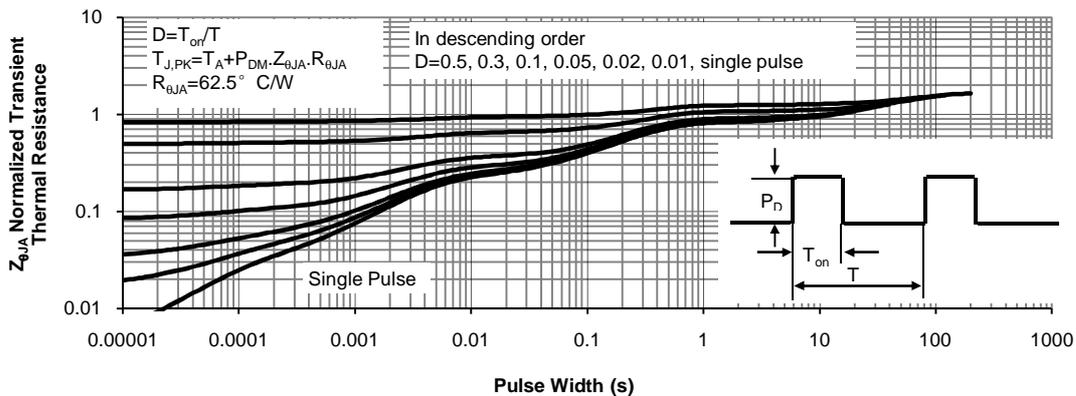
**Figure 8: Capacitance Characteristics**



**Figure 9: Maximum Forward Biased Safe Operating Area (Note E)**



**Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)**



**Figure 11: Normalized Maximum Transient Thermal Impedance**

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